

Description

This is a two-part, smooth, dark grey paste that cures to form a hard, durable polymer that is extremely thermally conductive, yet electrically insulating. It is very viscous because it is highly filled with thermally conductive ceramic powders for maximum thermal conductivity. It bonds well to metals, ceramics, glass, and most plastics used in electronic assemblies.

It has a convenient 1-to-1 mix ratio, a 45 minutes working life, and a moderate curing rate. At room temperature, it may achieve a minimal service cure in seven hours.

This product comes packaged in separate 3 mL syringes that can be accurately dispensed, or in 50 mL or 200 mL kits packaged in jars.

Applications & Usages

This product is designed to bond heat sinks, LED's, and other heat generating components in electronic assemblies. It is suitable for the manufacturing, repair, and hobbyist sectors. Use it when a thixotropic adhesive paste with maximum thermal conductivity and a moderate working life is required. For automatic dispensing applications, use the 8329TFM, which offers a lower viscosity at the cost of slightly lower thermal conductivity.

Benefits and Features

- **Thermal conductivity: 1.36 W/(m·K)**
- **1:1 mix ratio**
- **Working life: 45 minutes**
- **Cure time: 1 hour at 65 °C or 24 hours at room temperature**
- **Good adhesive strength**
- **Strong resistance to water, brine, acids, bases, and aliphatic hydrocarbons**
- **Room temperature storage**
- **Shelf life greater than two years**

ENVIRONMENT

- ✓ RoHS
- ✓ REACH compliant

ATTENTION! Forms non-reworkable permanent bonds.

Usage Parameters

Properties	Value
Working Life ^{a)}	45 min
Shelf Life ^{b)}	≥2 y
Min. Service Cure ^{c)}	7 h
Full Cure @25 °C [77 °F]	24 h
Full Cure @65 °C [149 °F]	1 h

a) Pot life for 100 g and room temperature.

b) Shelf life assumes the product is tightly capped and kept below 45 °C.

c) Minimal service cure at 25 °C [77 °F].

Temperature Ranges

Properties	Value
Constant Service Temperature	-65 to 165 °C [-85 to 329 °F]
Intermittent Temperature	-70 to 200 °C
Extrema ^{d)}	[-94 to 392 °F]
Storage Temperature of Unmixed Parts	22 to 27 °C [72 to 81 °F]

d) The temperature extremes that can be withstood for a short period of times.

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8329TCM

Properties of Cured 8329TCM

Physical Properties	Method	Value ^{a)}
Color	Visual	Dark Grey
Density @26 °C [79 °F]	ASTM D 1475	2.30 g/mL
Hardness	Shore D durometer	76-77D
Tensile Strength	ASTM D 638	10 N/mm ² [1 400 lb/in ²]
Elongation	"	1.8%
Compression Strength	ASTM D 695	34 N/mm ² [4 900 lb/in ²]
Lap Shear Strength (Aluminum 5052)	"	8.2 N/mm ² [1 200 lb/in ²]
Water Absorption	ASTM D 570	0.35%
Outgassing (Total Mass Loss) @24 h	ASTM E 595	3.54%
Water Vapor Release (WVR)	"	0.15%
Collectable Volatile Condensable Material	"	0.18%
Electric Properties	Method	Value
Breakdown Voltage @4.491 mm	ASTM D 149	29.0 kV
Dielectric Strength @4.491 mm	"	6.5 kV/mm [164 V/mil]
Breakdown Voltage @3.175 mm [1/8"]	Reference fit ^{b)}	24.3 kV
Dielectric Strength @3.175 mm [1/8"]		7.7 kV/mm [195 V/mil]
Volume Resistivity	ASTM D 257	9 x 10 ¹² Ω·cm
Surface Resistivity	"	3 x 10 ¹³ Ω
Dielectric Dissipation & Constant @1 kHz	ASTM D 150-98	dissipation, D constant, k' 0.025 5.43
Insulating		Yes
Conductive		No
Thermal Properties	Method	Value
Thermal Conductivity @25 °C	ASTM E 1461	1.36 W/(m·K)
@50 °C	"	1.34 W/(m·K)
@100 °C	"	1.28 W/(m·K)
Heat Deflection Temperature	ASTM D 648	42 °C [115 °F]
Glass Transition Temperature (T _g)	ASTM D 3418	46 °C [108 °F]
CTE ^{c)} Prior T _g	ASTM E 831	71 ppm/°C
CTE ^{c)} After T _g	ASTM E 831	131 ppm/°C
Specific Heat @25 °C [77 °F]		0.907 J/(g·K)

Note: Specifications are for epoxy samples that were cured at 65 °C for 1 hour. Additional curing time at room temperature was given to allow for optimum curing. Samples were conditioned at 23 °C and 50% RH prior to most tests.

a) N/mm² = MPa; lb/in² = psi

b) To allow comparison between products, the Tautscher equation was fitted to 3 experimental dielectric strengths and extrapolated to a standard reference thickness of 1/8" (3.175 mm).

c) Coefficient of Thermal Expansion (CTE) units are in ppm/°C = in/in/°C × 10⁻⁶ = unit/unit/°C × 10⁻⁶

Properties of Uncured 8329TCM

<i>Physical Property</i>	<i>Mixture (1A:1B)</i>	
Color	Dark Grey	
Density ^{a)}	2.47 g/mL	
Mix Ratio by Volume (A:B)	1:00:1.00	
Mix Ratio by Weight (A:B)	0.93:1.00	
Solids Content (w/w)	100%	
<i>Physical Property</i>	<i>Part A</i>	<i>Part B</i>
Color	Dark Grey	Dark Grey
Density	2.51 g/mL	2.43 g/mL
Flash Point	>149 °C [300 °F]	>148 °C [298 °F]
Viscosity	Thixotropic paste	Thixotropic paste

a) Calculated value based on measures densities of each part

b) Brookfield viscometer at 3 rpm for part A and 0.6 rpm for part B with spindle 7

Principal Components

Name	CAS Number
Part A: Bis-A Epoxide Resin	25068-38-6
Aluminum Oxide	1344-28-1
Zinc Oxide	1314-13-2
Boron Nitride	110043-11-5
Part B: tris-2,4,6-(dimethylaminomethyl) phenol	90-72-2
Mercaptan mixture	proprietary
Aluminum Oxide	1344-28-1
Zinc Oxide	1314-13-2
Boron Nitride	110043-11-5

Compatibility

Chemical—Once cured, the epoxy adhesive is inert under normal conditions. It will resist water and salt exposure.

It is expected to resist short term exposures to fuels or similar non-polar organic solvents, but it is not suitable for prolonged exposures. Avoid use with strong acids, strong bases, or strong oxidizers.

Adhesion—As seen in the substrate adhesion table, the 8329TCM epoxy adheres to many materials found on printed circuit assemblies; however, contaminants like water, oil, and greasy flux residues may affect adhesion. If contamination is present, clean the printed circuit assembly with electronic cleaner such as MG Chemicals 4050 Safety Wash, 406B Superwash, or 824 Isopropyl Alcohol.

For substrate substances with weak adhesion strengths, surface preparation such as sanding or pre-coating with a suitable primer may improve adhesion.



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Substrate Adhesion in Decreasing Order

<i>Physical Properties</i>	<i>Adhesion</i>
Steel	Stronger  Weaker
Aluminum	
Copper/Bronze	
Fiberglass	
Wood	
Paper, Fiber	
Glass	
Rubber	
Acrylic	
Polycarbonate	
Polypropylene ^{a)}	
Teflon ^{a)}	

a) Does not bond to polypropylene or Teflon

Storage

Store between 22 and 45 °C [72 and 113 °F] in dry area away from sunlight. Because some of the components are sensitive to air, always recap firmly when not in use to maximize shelf life.

Health, Safety, and Environmental Awareness

Please see the 8329TCM **Safety Data Sheet** (SDS) parts A and B for more details on transportation, storage, handling and other security guidelines.

Health and Safety: The 8329TCM parts can ignite if the liquid is both heated and exposed to flames.

Wear safety glasses or goggles and disposable polyvinyl chloride, neoprene, or nitrile gloves while handling liquids. Part B in may cause eye damage. Skin irritation and sensitization may occur if exposed over a long period of time. The epoxy will not wash off once cured. Wash hands thoroughly after use or if skin contact occurs. Do not ingest.

Use in well-ventilated area since vapors are strong smelling and may cause irritation of the respiratory tract in susceptible individuals.

The uncured product contains unbound marine pollutants. Dispose of material according to local, regional, national, and international regulation. The cured product is not expected to be environmentally hazardous.

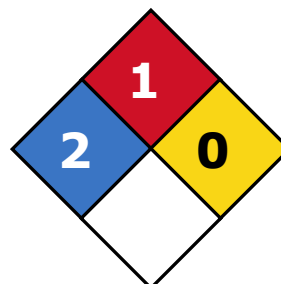
The cured epoxy adhesive presents no known hazard.

Part A

HMIS® RATING

HEALTH:	* 2
FLAMMABILITY:	1
PHYSICAL HAZARD:	0
PERSONAL PROTECTION:	

NFPA® 704 CODES

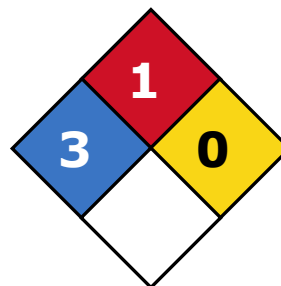


Part B

HMIS® RATING

HEALTH:	* 3
FLAMMABILITY:	1
PHYSICAL HAZARD:	0
PERSONAL PROTECTION:	

NFPA® 704 CODES



Approximate HMIS and NFPA Risk Ratings Legend:

0 (Low or none); 1 (Slight); 2 (Moderate); 3 (Serious); 4 (Severe)

Application Instructions

Follow the procedure below for best results. For mixing quantities that are less than 1 mL in size or for stricter stoichiometry control, mix by weight ratio instead (requires a high precision balance). Heat cure is recommended to get the best possible conductivity.

To prepare 1:1 (A:B) epoxy mixture by volume

1. Remove cap or cover.
2. Measure **one** part by volume of **A**.
3. Measure **one** part by volume of **B**.
4. Thoroughly mix the parts together with a stir stick until homogeneous.
5. Apply to with an appropriate sized stick for the application area.

NOTE: Remember to recap the syringe or container promptly after use.

TIP: Due to the high viscosity and abrasiveness of the filler, you may preheat part A and part B to increase the flow and improve air release, but this will decrease pot life. Note that the viscosities of the parts also decreases with mixing, so they will be most liquid-like and easily dispensed with constant mixing.



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To heat cure the 8329TCM epoxy

Put in oven at 65 °C [149 °F] for 15 minutes.

You can cure the epoxy faster by using higher temperatures of up to 160 °C [302 °F], which will provide a faster cure time of 7 min and optimum conductivity values.

TIP: Hair dryers are normally rated not to exceed 60 °C, so they can generally be used to accelerate the cure.

ATTENTION: Keep the curing temperature well below temperature limit of heat sensitive components that may be present. As a guideline, remember that commercial grade devices normally can be safely operated up to 70 °C, industrial grade up to 85 °C, and military grade up to 175 °C.

ATTENTION: Heat guns can easily exceed the temperature limits for your assembly: they should not be used.

To room temperature cure the 8329TCM epoxy

Let stand for 5 to 24 hours.

TIP: While the product can be cured at room temperature, the better conductive performance is achieved with heat curing.

Packaging and Supporting Products

<i>Cat. No.</i>	<i>Packaging</i>	<i>Net Volume</i>		<i>Net Weight</i>		<i>Packaging Weight</i>	
8329TCM-6ML	Syringe	6 mL	0.2 fl oz	14.8 g	0.52 oz	36 g	1.2 oz
8329TCM-50ML	Jar	50 mL	1.6 fl oz	123 g	4.35 oz	160 g	0.35 lb
8329TCM-200ML	Can	200 mL	6.76 fl oz	494 g	1.09 lb	500 g	1.2 lb

Note: Package weight are estimated and may vary based packaging used.

Technical Support

Contact us regarding any questions, improvement suggestions, or problems with this product. Application notes, instructions, and FAQs are located at www.mgchemicals.com.

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Warranty

M.G. Chemicals Ltd. warrants this product for 12 months from the date of purchase by the end user. *M.G. Chemicals Ltd.* makes no claims as to shelf life of this product for the warranty. The liability of *M.G. Chemicals Ltd.* whether based on its warranty, contracts, or otherwise shall in no case include incidental or consequential damage.

Disclaimer

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